

**I. The Claims Define Patentable Subject Matter**

The Office Action rejects claims 1, 3 and 29-31 under 35 U.S.C. §102(b) over U.S. Patent No. 5,255,430 to Tallaksen and claims 1-3, 10, 11 and 29-31 under 35 U.S.C. §102(b) over U.S. Patent No. 5,926,696 to Baxter et al. These rejections are respectfully traversed.

Neither Tallaksen nor Baxter disclose first and second flexible substrates in a taped form as in the invention of claims 1 and 29. The first flexible substrate is strengthened by adhering the second flexible substrate in a tape form to the first flexible substrate in a tape form. In this way, the plurality of the semiconductor device is maintained and the number of components is reduced. Thus, in the inventions of claims 1 and 29 it is possible to provide a high reliability in an inexpensive semiconductor device.

Both Tallaksen and Baxter are devoid of these features.

The Office Action rejects claim 8 under 35 U.S.C. §103(a) over Tallaksen in view of U.S. Patent No. 6,140,707 to Pleyps et al. This rejection is respectfully traversed.

As discussed above, claim 1 defines patentable subject matter. Claim 8 depends from claim 1 and thus also defines patentable subject matter.

The Office Action rejects claims 1-7, 9-11 and 27-31 under 35 U.S.C. §103(a) over U.S. Patent No. 6,324,067 to Nishiyama in view of U.S. Patent No. 5,646,828 to Degani et al. This rejection is respectfully traversed.

As previously discussed, independent claims 1 and 29 recite a first and second flexible substrate in tape form. This feature is neither disclosed or suggested by Nishiyama or Degani.

With respect to claim 4, Nishiyama fails to disclose a conductive layer electrically insulated from the wiring pattern as in the invention of claim 4. Instead Nishiyama discloses six conductive layers electrically connected to each other. See, e.g., col. 4, lines 13-17.

The Office Action rejects claim 8 under 35 U.S.C. §103(a) over Nishiyama in view of Degani and further in view of Plepys. This rejection is respectfully traversed.

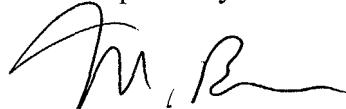
As previously discussed, claim 8 depends from claim 1. Thus claim 8 defines patentable subject matter.

**II. Conclusion**

In view of the foregoing, Applicant submits that this application is in condition for allowance. Favorable consideration and prompt allowance are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact Applicant's undersigned representative at the telephone number listed below.

Respectfully submitted,



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Attachment:

Appendix  
Petition for Extension of Time

Date: February 24, 2003

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<b>DEPOSIT ACCOUNT USE AUTHORIZATION</b> Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461
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## APPENDIX

## Changes to Claims:



The following is a marked-up version of the amended claims:

1. (Twice Amended) A semiconductor device comprising:  
a semiconductor chip on which a plurality of electrodes are formed;  
a first flexible substrate in a tape form on which a wiring pattern is formed and  
on which the semiconductor chip is mounted;  
a plurality of external terminals electrically connected to the electrodes with  
the wiring pattern interposed; and  
a second flexible substrate in a tape form adhered to the first flexible substrate  
by a resin avoiding the semiconductor chip,  
wherein the second flexible substrate is formed of the same material as the  
first flexible substrate.
8. (Amended) The semiconductor device as defined in claim 3,  
wherein the electrodes of the semiconductor chip are electrically connected to  
the wiring pattern by an anisotropic conductive material having electrically conductive  
particles dispersed in an adhesive; and the resin.  
~~wherein the first and second flexible substrates are adhered to each other by  
the anisotropic conductive material.~~
9. (Amended) The semiconductor device as defined in claim 3,  
~~wherein the first and second flexible substrates are adhered to each other by a  
resin; and~~  
wherein the resin is provided on a surface of the first flexible substrate on  
which the wiring pattern is formed, and is in close contact with a surface of the wiring pattern  
facing the second flexible substrate and edge surfaces of the wiring pattern.

29. (Amended) A semiconductor device comprising:

    a semiconductor chip on which a plurality of electrodes are formed;

    a first flexible substrate in a tape form on which a wiring pattern is formed and on which the semiconductor chip is mounted;

    a plurality of external terminals electrically connected to the electrodes with the wiring pattern interposed; and

    a second flexible substrate in a tape form adhered to the first flexible substrate by a resin avoiding the semiconductor chip,

    wherein the second flexible substrate is formed of a material having a coefficient of thermal expansion substantially equal to a coefficient of thermal expansion of a material of the first flexible substrate.